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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No
Priority Filing Date November 21, 2001
Inventor Rickie C. Lake
Assignee Micron Technology, Inc.
<u>Priority</u> Group Art Unit
Priority Examiner J. Haran
Attorney's Docket No
Title: Thin Profile Battery Bonding Method, Method of Conductively Interconnecting
Electronic Components, Battery Powerable Apparatus, Radio Frequency
Communication Device, and Electric Circuit

INFORMATION DISCLOSURE STATEMENT

References - - See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, copending application of the above-identified application. The above-identified application is a continuation application of co-pending application Serial No. 09/989,960, filed November 21, 2001, upon which the above-identified application relies for a priority date under 35 U.S.C. §120. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. §1.98(d) and MPEP §609(2). As a courtesy, Applicant submits copies of the cited articles for review.

Citation of these references is respectfully requested.

Respectfully submitted,

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Date: Fel 26, 2008

Deepak Malhotra Reg. No. 33,560

U.S. DEPARTMENT OF COMMERCE SERIAL NO. Form PTO-1449 ATTY. DOCKET NO. PATENT AND TRADEMARK OFFICE Filed Herewith MI40-371 LIST OF ART CITED BY APPLICANT APPLICANT Rickie C. Lake (Use several sheets if necessary) FILING DATE (Priority) GROUP Filed Herewith U.S. PATENT DOCUMENTS Date Class Subclass Filing Date *Examiner Document Name Number If Appropriate Initial AA 4,051,161 9/27/77 Proskow ΑB 4,208,005 6/17/80 Nate et al. AC 4,470,883 9/11/84 Eichelberger et al. AD 5,558,679 9/24/96 Tuttle 5,601,941 2/11/97 ΑE Tuttle ΑF 5,843,251 12/1/98 Tsukagoshi et al. 4,975,221 12-4-90 AG Chen et al. ΑH 5,362,421 11/08/94 Kropp et al. Αŀ 5,728,473 03/17/98 Inoue et al. ΑJ 5,532,024 07/02/96 Arndt et al. 07/21/98 5,783,465 AK Canning et al. FOREIGN PATENT DOCUMENTS Translation Document Date Country Class Subclass Number Yes No AL AM AN ΑO ΑP OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) ΑQ Product Information Brochure, "Information About Organofunctional Silane Chemicals," Dow Corning Corporation (date unknown) AR Product Information Brochure, Information About Dow Corning @ Z-6040 Silane," Dow Corning Corporation (1996) Misczyk et al. Laboratory evaluation of epoxy coatings with an adhesion promoter by impedance. Progress in Organic Coatings 25 (1995) 357-363. AS ΑT Gu et al. Effect of deposition conditions for y-aminopropyltriethoxy silane on adhesion between copper and epoxy resins. Applied Surface Science 115 (1997) 66-73. ΑU Lin et al. Synthesis of novel trifunctional epoxy resins and their modification with polydimethylsiloxane for electronic application. Elsevier Science Ltd. PH: s0032-3861 (96)00713-6 (1996) EXAMINER DATE CONSIDERED *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.